

MECHANICAL CASE OUTLINE

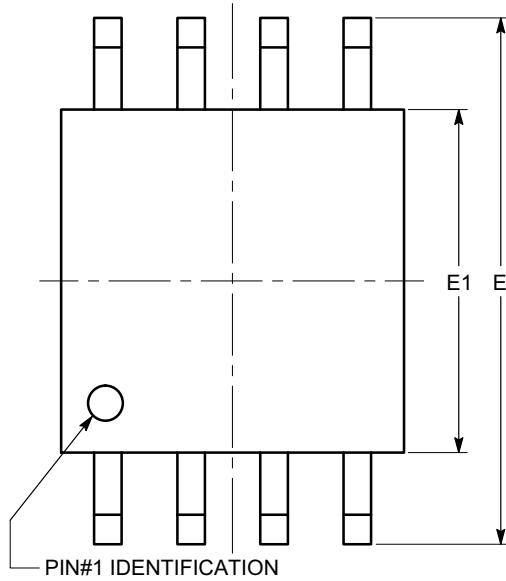
PACKAGE DIMENSIONS

ON Semiconductor®



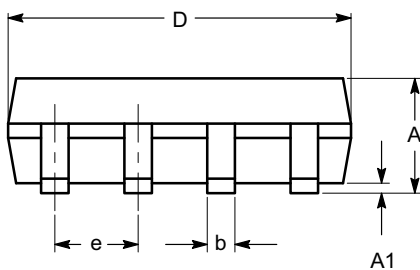
SOIC-8, 208 mils
CASE 751BE-01
ISSUE O

DATE 19 DEC 2008

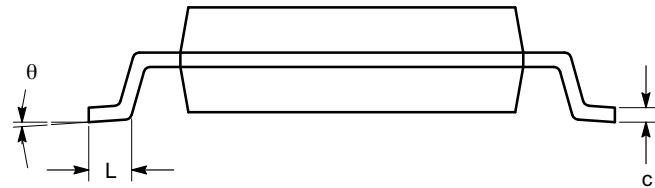


TOP VIEW

SYMBOL	MIN	NOM	MAX
A			2.03
A1	0.05		0.25
b	0.36		0.48
c	0.19		0.25
D	5.13		5.33
E	7.75		8.26
E1	5.13		5.38
e	1.27 BSC		
L	0.51		0.76
θ	0°		8°



SIDE VIEW



END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with EIAJ EDR-7320.

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DESCRIPTION:	SOIC-8, 208 MILS	PAGE 1 OF 2

